

D

C

B

A

D

B

A

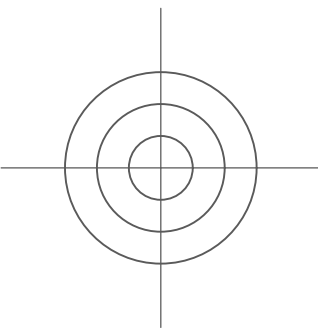
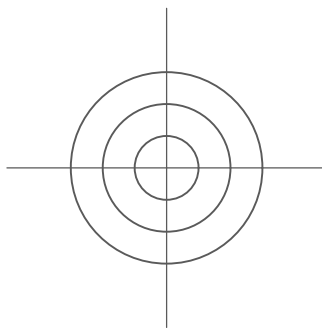
1

2

3

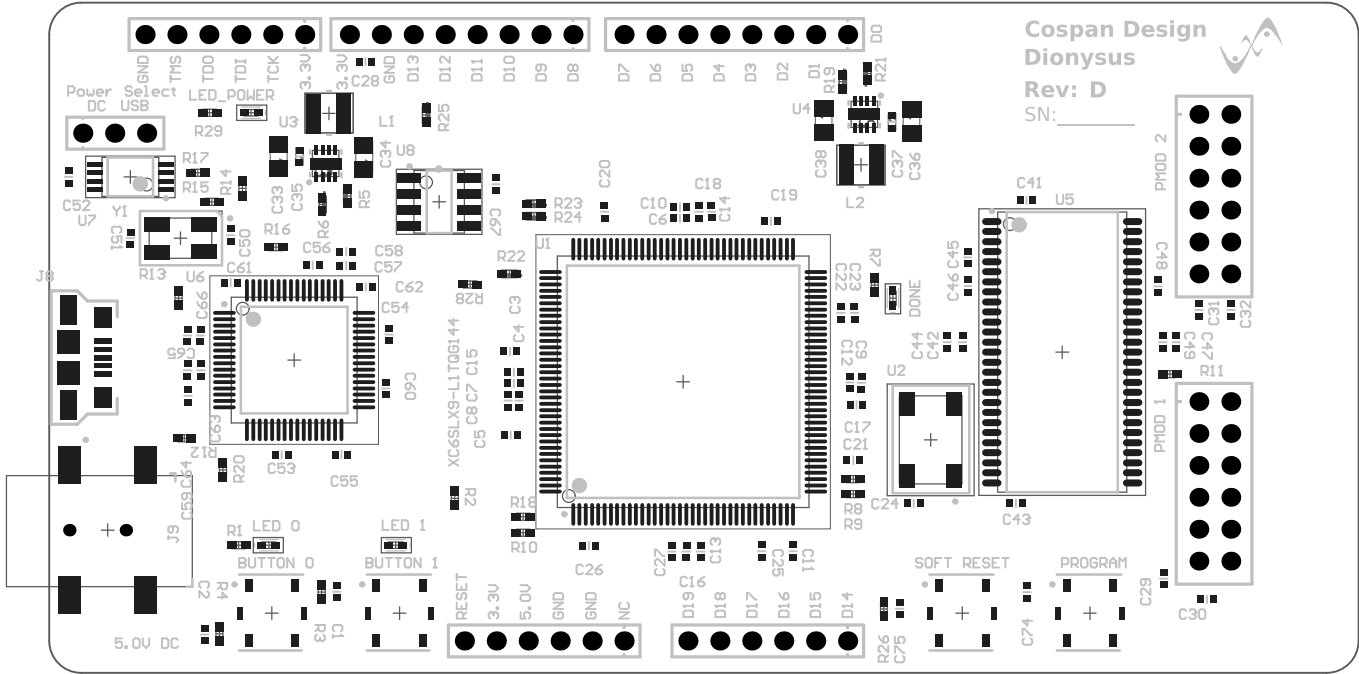
4

5



Layer Stack Up Detail for: Dionysus.PcbDoc

Layer Name
Component Side: 1.0 Oz
Ground Plane: 1.0 Oz
Power Plane: 1.0 Oz
Solder Side: 1.0 Oz

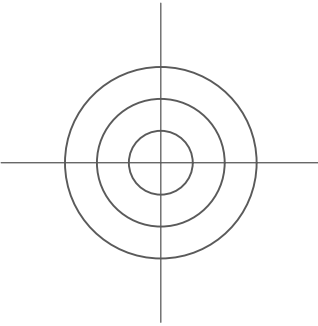


Fabrication Notes

- Overall board height: 62mils
- 20mil pullback on inner planes
- 1.0 Oz copper on top and bottom
- 1.0 Oz copper on internal signal, power and ground layers

Design Notes

- Unless otherwise stated all dimensions are in mils



LAYER - GERBER LAYERS - DESCRIPTION

GTO - TOP SILKSCREEN

- MECHANICAL LAYERS
- 01 Component Outline
  - 02 PCB Boundary
  - 03 Pinout ID
  - 04
  - 05
  - 06 Fabrication Notes
  - 07 Component Designators
  - 08
  - 09
  - 10
  - 11 Design Information
  - 12 Dimension
  - 13 Height Information
  - 14
  - 15 Assembly
  - 16 Sheet

Multi-Layer

B  
Size

Dave McCoy	Cospan Design			
Dave McCoy				
9/11/2012	D	9/11/2012	D	
1:1	Dionysus.PcbDoc		Sheet 1	of 1

1

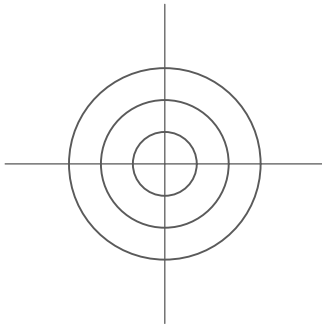
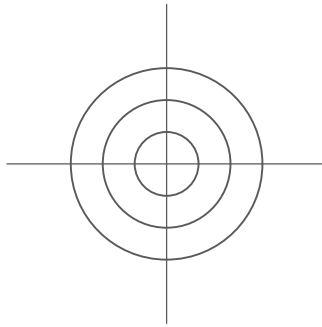
2

3

4

5

6



Layer Stack Up Detail for: Dionysus.PcbDoc

Layer Name
Component Side: 1.0 Oz
Ground Plane: 1.0 Oz
Power Plane: 1.0 Oz
Solder Side: 1.0 Oz

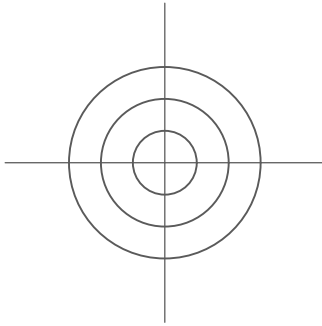


Fabrication Notes

- Overall board height: 62mils
- 20mil pullback on inner planes
- 1.0 Oz copper on top and bottom
- 1.0 Oz copper on internal signal, power and ground layers

Design Notes

- Unless otherwise stated all dimensions are in mils



LAYER - GERBER LAYERS - DESCRIPTION

GB0 - BOTTOM SILKSCREEN

- MECHANICAL LAYERS
- 01 Component Outline
  - 02 PCB Boundary
  - 03 Pinout ID
  - 04
  - 05
  - 06 Fabrication Notes
  - 07 Component Designators
  - 08
  - 09
  - 10
  - 11 Design Information
  - 12 Dimension
  - 13 Height Information
  - 14
  - 15 Assembly
  - 16 Sheet

Multi-Layer

B  
Size

Dave McCoy	Cospan Design		
Dave McCoy			
9/11/2012	D	9/11/2012	D
1:1	Dionysus.PcbDoc		
	Sheet 1 of 1		